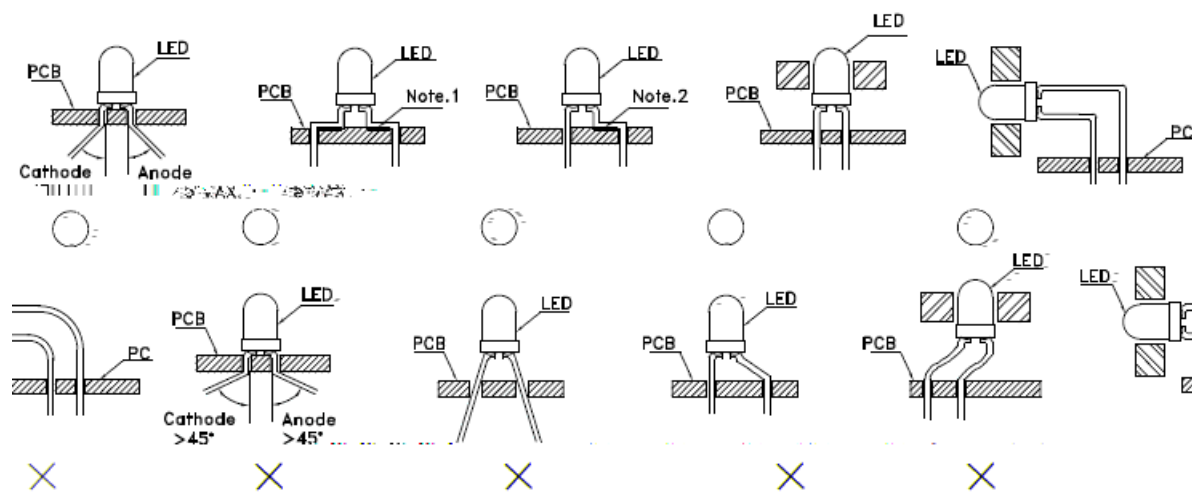




PACKAGE

LED MOUNTING METHOD

- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.(Fig.1)



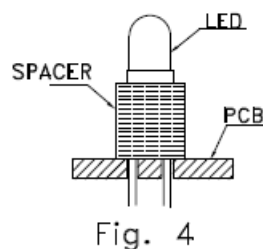
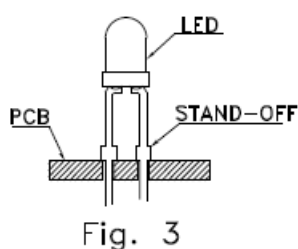
-2: Do not route PCB

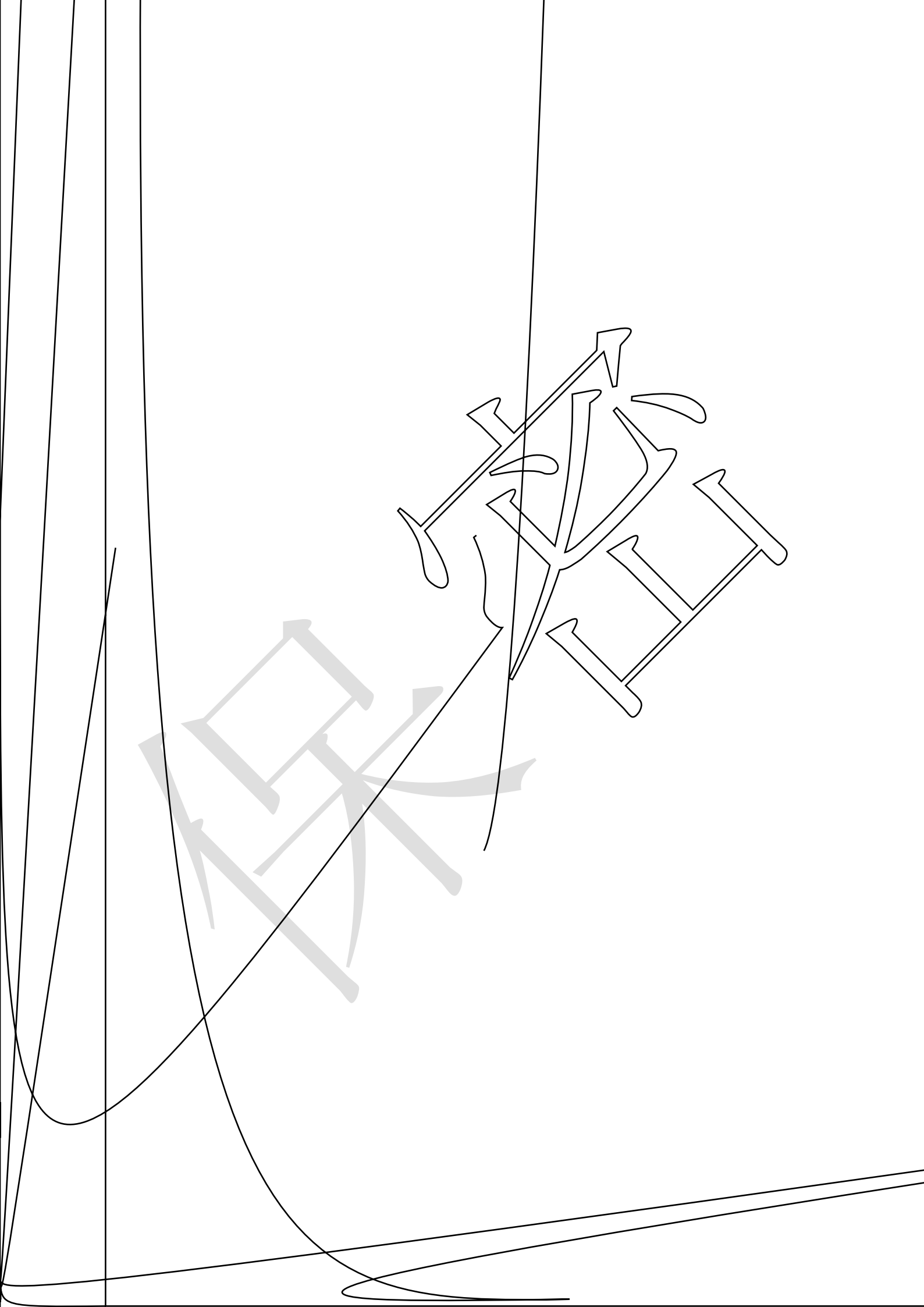
Trace in the contact area between the lead frame and the PCB to prevent short-circuit.

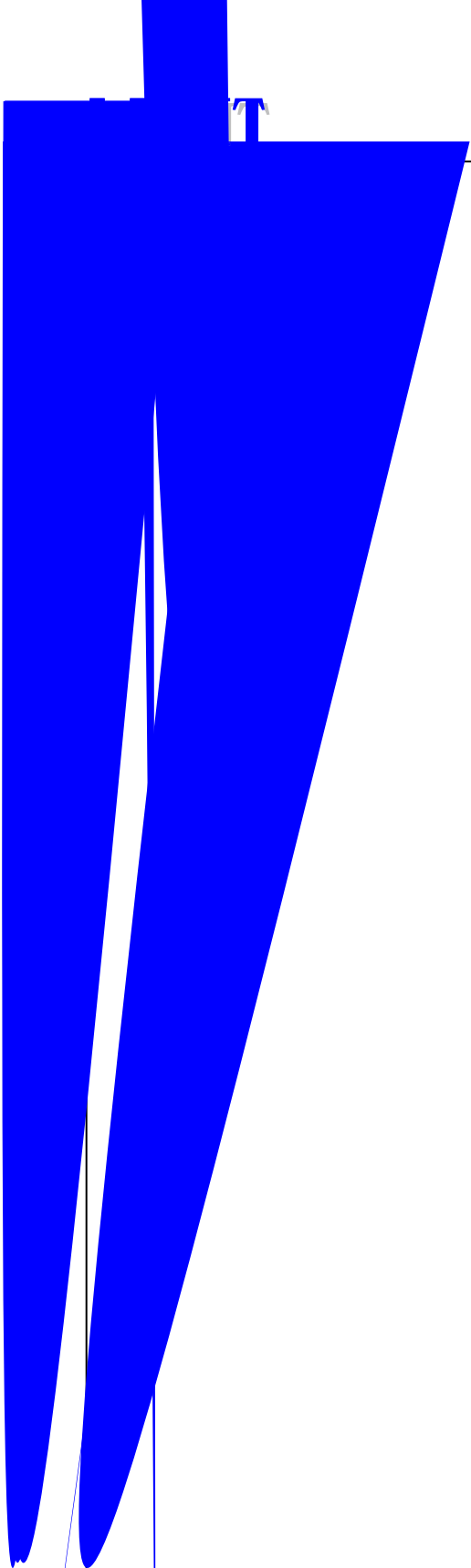
- When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2)



- Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.







T

Infrared Emitting Diode Specification

●Commodity: Infrared emitting diode

●Intensity Bin Limits (At 50mA)

BIN CODE	Min.(mW/sr)	Max.(mW/sr)
27	10.5	14
28	14	18.5